20 V, 4.0 A, Low V_{CE(sat)} NPN Transistor

ON Semiconductor's e²PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- AEC-Q101 Qualified and PPAP Capable
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*



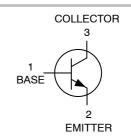
ON Semiconductor®

http://onsemi.com

20 VOLTS 4.0 AMPS NPN LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 37 m Ω



SOT-23 (TO-236) CASE 318 STYLE 6



MARKING DIAGRAM



VD = Specific Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NSS20201LT10	G SOT-23 (Pb-Free)	3,000 / Tape & Reel
NSV20201LT10	G SOT-23 (Pb-Free)	3,000 / Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Мах	Unit
Collector-Emitter Voltage	V _{CEO}	20	Vdc
Collector-Base Voltage	V _{CBO}	20	Vdc
Emitter-Base Voltage	V _{EBO}	6.0	Vdc
Collector Current – Continuous	Ι _C	2.0	А
Collector Current – Peak	I _{CM}	4.0	А
Electrostatic Discharge	ESD	HBM Class 3B MM Class C	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P _D (Note 1)	460 3.7	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 1)	270	°C/W
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above 25°C	P _D (Note 2)	540 4.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 2)	230	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

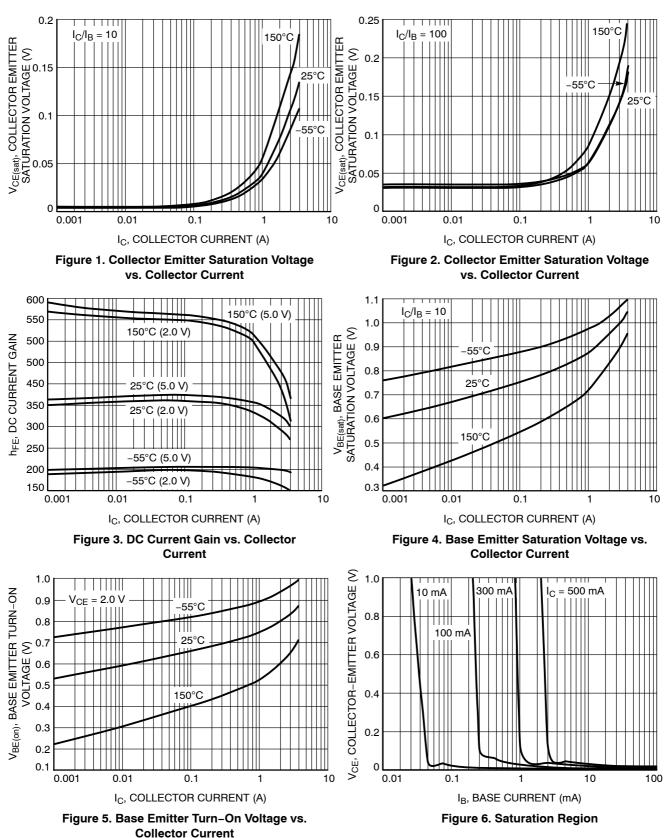
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-4 @ 100 mm², 1 oz. copper traces. 2. FR-4 @ 500 mm², 1 oz. copper traces.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

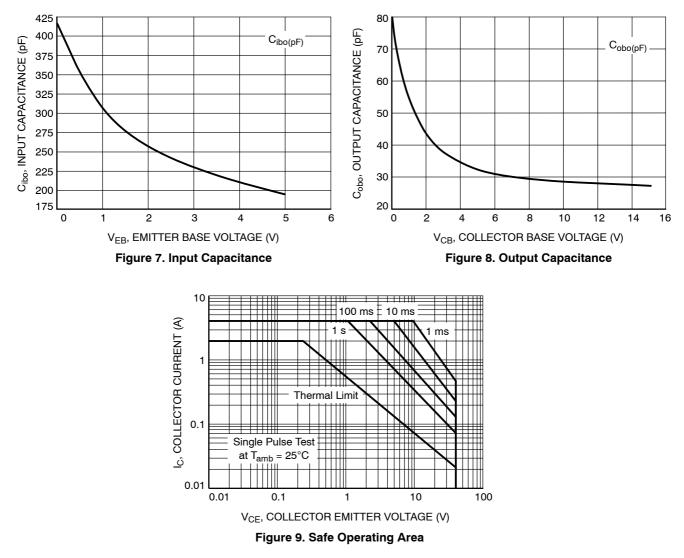
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS				•	•
Collector – Emitter Breakdown Voltage $(I_C = 10 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	20	-	_	Vdc
Collector – Base Breakdown Voltage $(I_{C} = 0.1 \text{ mAdc}, I_{E} = 0)$	V _{(BR)CBO}	20	-	_	Vdc
Emitter – Base Breakdown Voltage $(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	6.0	-	_	Vdc
Collector Cutoff Current ($V_{CB} = 20 \text{ Vdc}, I_E = 0$)	Ісво	_	-	0.1	μAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc)	I _{EBO}	-	-	0.1	μAdc
ON CHARACTERISTICS				•	
$ \begin{array}{l} \text{DC Current Gain (Note 3)} \\ (I_{C} = 10 \text{ mA}, \text{V}_{CE} = 2.0 \text{ V}) \\ (I_{C} = 500 \text{ mA}, \text{V}_{CE} = 2.0 \text{ V}) \\ (I_{C} = 1.0 \text{ A}, \text{V}_{CE} = 2.0 \text{ V}) \\ (I_{C} = 2.0 \text{ A}, \text{V}_{CE} = 2.0 \text{ V}) \end{array} $	h _{FE}	200 200 200 200	_ 360 _ _		
$\begin{array}{l} \mbox{Collector} - \mbox{Emitter Saturation Voltage (Note 3)} \\ (I_{C} = 0.1 \mbox{ A}, I_{B} = 0.010 \mbox{ A}) \\ (I_{C} = 1.0 \mbox{ A}, I_{B} = 0.100 \mbox{ A}) \\ (I_{C} = 1.0 \mbox{ A}, I_{B} = 0.010 \mbox{ A}) \\ (I_{C} = 2.0 \mbox{ A}, I_{B} = 0.200 \mbox{ A}) \end{array}$	V _{CE(sat)}	- - -	0.004 0.037 0.060 0.072	0.010 0.050 0.090 0.100	V
Base – Emitter Saturation Voltage (Note 3) $(I_C = 1.0 \text{ A}, I_B = 10 \text{ mA})$	V _{BE(sat)}	_	0.760	0.900	V
Base – Emitter Turn-on Voltage (Note 3) (I _C = 1.0 A, V _{CE} = 2.0 V)	V _{BE(on)}	_	0.760	0.900	V
Cutoff Frequency ($I_C = 100 \text{ mA}, V_{CE} = 5.0 \text{ V}, f = 100 \text{ MHz}$)	f _T	150	-	_	MHz
Input Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	Cibo	-	-	450	pF
Output Capacitance (V _{CB} = 3.0 V, f = 1.0 MHz)	Cobo	-	-	45	pF
SWITCHING CHARACTERISTICS					
Delay (V _{CC} = 15 V, I_C = 750 mA, I_{B1} = 15 mA)	t _d	-	-	100	ns
Rise (V_{CC} = 15 V, I_{C} = 750 mA, I_{B1} = 15 mA)	tr	_	-	100	ns
Storage (V _{CC} = 15 V, I _C = 750 mA, I _{B1} = 15 mA)	t _s	_	-	500	ns
Fall (V _{CC} = 15 V, I _C = 750 mA, I _{B1} = 15 mA)	t _f	-	-	110	ns

3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle \leq 2%.



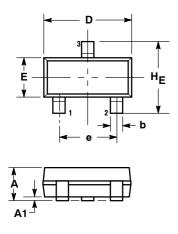
TYPICAL CHARACTERISTICS

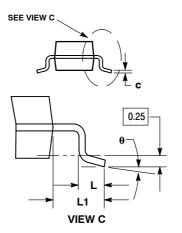
TYPICAL CHARACTERISTICS



PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AP





NOTES:

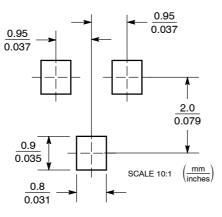
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- A. DIMENSIONS OF DADE INFLEMENT. PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 6:

PIN 1. BASE 2. EMITTER 3. COLLECTOR

SOLDERING FOOTPRINT



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